# **Special Issue**

# **Bioinspired 3D Printing in 2021**

# Message from the Guest Editor

Additive manufacturing (three\dimensional (3D) printing) has created new opportunities for manipulating and mimicking the intrinsically multiscale, multimaterial, and multifunctional structures in nature. Understanding natural structures and replicating them by 3D printing for various engineering applications will lead us to drive the biomimicry field forward. Meanwhile, the fabrication challenges presented by biomimicry will lead to more novel biomimetic 3D printing processes. This Special Issue will focus on research advances in the areas of bioinspired 3D printing for future engineering systems. The growth of bioinspired 3D printing technology will open intriguing perspectives for developing bioinspired materials and structures on the basis of novel 3D printing processes together with new computer-aided design and simulation methods.

### **Guest Editor**

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## Deadline for manuscript submissions

closed (30 November 2021)



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#### Editor-in-Chief

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